

# JOHN PETER STEVENSON

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## EDUCATION

**Stanford University** 2008 – 2014  
Ph.D. Electrical Engineering

Thesis: *Fine-Grain In-Memory Deduplication for Large-Scale Workloads*

**Stanford University** 2000 – 2002  
M.S. Electrical Engineering

Focus on circuit design and semiconductor physics

**U.S. Naval Academy** 1996 – 2000  
B.S. Control Systems Engineering  
Graduated 1st in academic standing

## HONORS & AWARDS

**Y-Combinator** 2025  
PAX Markets, Inc., YC W25 batch.

**Best Paper** 2012  
Sparse Matrix-Vector Multiply on the HICAMP Architecture, International Conference on Supercomputing

**Best Startup Project** 2011  
Stanford MS&E-273: Punch Mobile

**David Cheriton Fellow** 2008 – 2014  
Stanford Graduate Fellowship

**SOE Fellow** 2000 – 2002  
Stanford School of Engineering Fellowship

**Ward Prize** 2000  
Best undergraduate research for a multi-aperture camera array

**PKP NHS Fellow** 2000  
Phi Kappa Phi National Honor Society Graduate Study Fellowship

**Rhodes Finalist** 1999

**Eagle Scout** 1996

## EXPERIENCE

**PAX Markets** 2025 – Present  
CEO & Founder | Redwood City, CA

PAX is a new crypto exchange, on a chip. PAX provides unprecedented value to institutional trading participants: for HFT operators, PAX offers fee-based ultra-low latency exchange integrated order placement. All other market participants trade with zero-fees.

**Jaguar Technologies** 2024 – 2024  
Lead Quantitative Researcher | Menlo Park, CA

Developed  $\alpha$  models: short term price predictions for crypto markets. Developed low latency high frequency crypto trading platform.

**Pixie Labs & New Relic** 2020 – 2024  
Founding & Principal Engineer | San Francisco, CA

Led development of eBPF performance profiler. Developed continuous performance regression testing framework.

**Citadel Securities** 2016 – 2020  
Quantitative HW/SW Developer | Chicago, IL

Hardware software co-design for low latency trading. Implemented machine learning algorithms in FPGA. Wrote hardware emulator for model training.

**Intel** 2014 – 2016  
Silicon Architect | Santa Clara, CA

Developed next generation memory technology as a member of the HICAMP team acquired in 2014. Wrote CPU cache performance simulator to validate key aspects of the technology. Contributed micro-architectural optimizations.

**HICAMP Systems** 2009 – 2014  
Member of Technical Staff | Menlo Park, CA

Member of seven person engineering team, firm and technology acquired by Intel in 2014. Contributed to FPGA implementation of next generation CPU memory controller.

**U.S. Naval Academy** 2006 – 2008  
Electrical Engineering Faculty | Annapolis, MD

As an officer faculty member, taught undergraduate engineering major and core curriculum classes on circuit analysis, logic design, and wireless.

**USS Los Angeles (SSN-688)** 2003 – 2006  
Officer | Honolulu, HI

As Officer of the Deck, responsible for all operations submerged, surfaced, and in port, in lieu of the ship's Captain. As Engineering Officer of the Watch, responsible for all nuclear power plant operations, in lieu of the ship's Engineer. Supervised a shipboard division.

## PUBLICATIONS

**SITM** 2014

*SI-TM: Reducing Transactional Memory Abort Rates through Snapshot Isolation*

H. Litz, D. Cheriton, A. Firoozshahian, O. Azizi, J.P. Stevenson, ASPLOS 2014

**SpMV on HICAMP** 2012

*Sparse Matrix-Vector Multiply on the HICAMP Architecture*

J.P. Stevenson, A. Firoozshahian, A. Solomatnikov, M. Horowitz, and D. Cheriton, ICS 2012

Winner of Best Paper Award at International Conference on Supercomputing, 2012

**HICAMP** 2012

*HICAMP: Architectural Support for Efficient Concurrency-Safe Shared Structured Data Access*

D. Cheriton, A. Firoozshahian, A. Solomatnikov, J.P. Stevenson, and O. Azizi, ASPLOS 2012

**CPU db** 2012

*CPU db: Recording Microprocessor History*

A. Danowitz, K. Kelley, J. Mao, J.P. Stevenson, and M. Horowitz, CACM 2012

**IR for ChipGen** 2011

*Intermediate Representations for Controllers in Chip Generators*

K. Kelley, M. Wachs, A. Danowitz, J.P. Stevenson, S. Richardson, M. Horowitz, DATE 2011

**CPU Co-Optimization** 2010

*An Integrated Framework for Co-Optimization of Architecture and Circuits*

O. Azizi, A. Mahesri, J.P. Stevenson, N. Zhou, S.J. Patel, and M. Horowitz, DATE 2010

## PATENTS

**Exchange Integrated Order Placement** 2024

J.P. Stevenson

**Customized Memory Deduplication** 2018

C. Egbert, A. Firoozshahian, M. Maddury, J.P. Stevenson, H. Neefs, O. Azizi

**Hardware-Assisted Paging Mechanisms** 2018

A. Firoozshahian, O. Azizi, C. Egbert, D. Hansen, A. Kleen, M. Maddury, M. Madhav, A. Solomatnikov, J.P. Stevenson

**Searchable Hot Content Cache** 2016

Omid Azizi, A. Solomatnikov, A. Firoozshahian, J.P. Stevenson, M. Maddury

## PROJECTS

**Zest – Memory Deduplicator for Linux** 2012 – 2016

Using LiME, zest counts duplicates in DRAM memory. Captures a snapshot of physical memory from a live instance of Linux. Performs post-mortem fine-grain deduplication to show the benefit of deduplicated memory systems. Shows that memory capacity is increased by over 2x in many common datacenter applications.

**Hash-Stats** 2014

Overflow Statistics for Large Hash Tables

Table utilization and table overflows are critical issues for large hash tables. Using published theoretical results, it provides simple scripts to guide the practicing engineer when implementing a large hash table.

<https://github.com/etep/hash-stats>

**Stanford Circuit Optimization Tool** 2008 – 2012

Using convex optimization, optimizes digital circuit design for latency and power. Integrates with industry standard tools such as SPICE.

<http://github.com/etep/scot>

**Punch Mobile** 2011

Electronic payment processing with integrated consumer loyalty. Provided significant cost savings by disintermediating the credit card payment network using a direct consumer-to-business (C2B) back-end. Voted as top project by VC panel.

**SIMD Floating Point Adder** 2001

Designed and taped out a fully functional 1x32 / 2x16 bit SIMD floating point adder with IEEE compliant rounding for Stanford independent projects in VLSI, EE-271. Silicon fabricated by TSMC in 0.5 $\mu$ m technology.